

Material Declaration Report

Package Type:	MSOP 8L
Pericom Package Code:	U8(Pb-free)
RoHS Compliance:	Yes
Applicable Exemption:	N/A

Component Weight (mg):	22.110
Termination Plating:	Matte Tin
JESD 97 Pb-free Category:	e3
Plating Thickness (um):	10-20
Tin Whisker Mitigation:	Anneal, 150C/1hr

MSL Rating:	1
Peak Body Temp (C):	260
Max Time (sec):	40
Reflow Cycles:	3
Rev Date:	6/4/2008

Homogeneous Material Declaration

MATERIAL ITEM	MATERIAL WEIGHT(mg)	ASSEMBLY SUBCON	MATERIAL COMPOSITION	CAS NO.	COMPOSITION %	COMPOSITION WEIGHT(mg)
MOLD COMPOUND	7.743	UTL	Silica Fused	60676-86-0	88.000	6.8140
			Epoxy Resin	Proprietary	5.000	0.3872
			Phenolic Resin	Proprietary	4.500	0.3484
			Epoxy, Cresol Novolac	29690-82-2	2.000	0.1549
			Carbon Black	1333-86-4	0.500	0.0387
LEADFRAME	12.886		Copper	7440-50-8	95.140	12.2599
			Nickel	7440-02-0	3.200	0.4124
			Silver	7440-22-4	0.760	0.0979
			Silicon	7440-21-3	0.725	0.0934
			Magnesium	7439-95-4	0.175	0.0226
SILICON DIE	0.644		Silicon (Si)	7440-21-3	99.192	0.6385
			Non-hazardous Metal	Proprietary	0.808	0.0052
DIE ATTACH EPOXY	0.159		Silver	7440-22-4	80.000	0.1269
			Functionalized Urethane	72869-86-4	8.000	0.0127
			Diester Resin	94-80-4	7.000	0.0111
			Epoxy Resin	Proprietary	5.000	0.0079
GOLD WIRE	0.115		Gold(Au)	7440-57-5	99.990	0.1150
			Impurities	-	0.010	0.0000
SOLDER PLATING	0.563		Tin (Sn)	7440-31-5	99.990	0.5632
			Impurity	-	0.010	0.0001

NOTE: The device contents disclosed are approximated and are based on engineering estimates.

3rd Party Analysis Results (PPM)

MATERIAL	Pb	Hg	Cr+6	Cd	PBB	PBDE
Mold Compound	<2	<2	<2	<2	<5	<5
Leadframe	<50	<2	<2	<2	<5	<5
Device Silicon Die	<2	<2	<2	<2	<5	<5
Die Attach Epoxy	<2	<2	<2	<2	<5	<5
Gold Wire	<2	<2	<2	<2	<5	<5
Solder Plating	<50	<2	<2	<2	<5	<5

ROHS MATERIAL COMPOSITION DECLARATION

EU RoHS Directive 2002/95/EC and China RoHS Directive SJ/T11363-2006	Declaration Statement:	Quantity limit of 0.1% (1000 PPM) by mass in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium(Cr+6), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE); and Quantity limit of 0.01% (100 PPM) for Cadmium				
		Pb	Hg	Cr+6	Cd	PBB
	<1000ppm	<1000ppm	<1000ppm	<100ppm	<1000ppm	<1000ppm
	O	O	O	O	O	O

O: Indicates that this toxic or hazardous substance contained in all of the homogeneous materials for this part is below the limit requirement in SJ/T11363-2006.
X: Indicates that this toxic or hazardous substance contained in at least one of the homogeneous materials used for this part is above the limit requirement in SJ/T11363-2006.